IN THE CLAIMS

Claims 1-14 (canceled).

Claim 15 (previously amended). A method for mounting multiple semiconductor dies on a single leadframe having fingers, comprising:

stacking at least two semiconductor dies having substantially the same rectangular dimensions on top of one another such that one of said dies is mounted on top of the leadframe fingers and the other of said dies is mounted on the die mounted on the leadframe fingers; and

wire bonding each of said semiconductor dies to the same leadframe fingers.

Claim 16 (previously amended). The method of claim 15, wherein one of said semiconductor dies is mounted back to back on the other of said semiconductor dies.

Claim 17 (previously amended). The method of claim 16, wherein one of said semiconductor dies is adhered to the other of semiconductor dies by an adhesive layer.

Claim 18 (original). The method of claim 15, wherein a first semiconductor die has a lead-on-chip configuration.

Claim 19 (original). The method of claim 15, wherein one of said dies is secured to said leadframe and the other of said dies is secured to the die secured to the leadframe.

Claim 20 (original). The method of claim 15, further comprising wirebonding the semiconductor dies to the leadframe, said dies having facing sides and outwardly facing sides by extending wires to bond pads on the outwardly facing sides of said die.

Claim 21 (previously amended). A method of connecting multiple semiconductor dies having bonding pads and a single leadframe having lead fingers, comprising:

locating a first semiconductor die on the lead fingers of the leadframe;

stacking a second semiconductor die on said first semiconductor die; and

electrically connecting the bonding pads of the semiconductor dies to the same lead fingers of the leadframe.

Claim 22 (original). The method of claim 21, further comprising encapsulating the semiconductor dies and the leadframe in a single package body.

Claims 23-31 (canceled).

32 (currently amended). A method for mounting multiple semiconductor dies on a single leadframe having fingers, comprising:

stacking first and second semiconductor dies having substantially the same rectangular dimensions on top of one another;

mounting the first semiconductor die on a leadframe finger; [and]

mounting the second semiconductor die only on said first semiconductor die; and

electrically connecting bonding pads on each of said semiconductor dice to the same lead fingers of the leadframe.

33 (previously new). The method of claim 32 including wire bonding the first and second semiconductor dies to the leadframe.

34 (previously new). The method of claim 32 wherein the first semiconductor die is mounted back to back on the second semiconductor die.

35 (previously new). The method of claim 34 wherein the first semiconductor die is adhered to the second semiconductor die by an adhesive layer.